

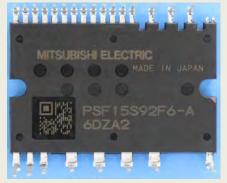
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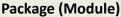
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MITSUBISHI PSF15S92F6 SIC INTELLIGENT POWER MODULE ANALYSIS REPORT

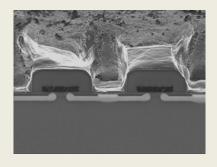
September 2017. LTEC Corporation released a detailed structure and process analysis report of the PSF15S92F6 Dual Inline Package Intelligent Power Module (DIPIPM). This device improves R_{ON} by 70% relative to a conventional Si power device.







Die (SiC OSFET)



SiC MOSFET cross-section

Device features

- Max. operating voltage: 600V, rated DC Drain current ID @25°C = 15A
- Very low specific On-resistance, R_{ON} x A= $500m\Omega$ x mm^2

The report has two individually purchasable sections: Structure Analysis and a Process Analysis sections. The 100-page Structure Analysis section reveals the physical construction of the device, including EDX materials analysis, and many other fine details. The 24-page Process Analysis section includes manufacturing process flow, the estimated number of photomasking steps, and the impurity concentration of the epitaxial layer.

Structure analysis report: \$5,000 Process analysis report: \$5,000

Contact LTEC Corporation

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